

AN 1992-017537 [03] WPIDS  
 DNN N1992-013312 DNC C1992-007560  
 TI Ductile **copper-phosphorus** solder alloy - contains  
 silver, **tin**, indium and manganese, tungsten, iron etc. for  
 improved cold forming properties.  
 DC M23 M26 P55  
 IN LUGSCHEIDE, E; MALIKOWSKI, W; WEISE, W; ZHUANG, H; ZIMMERMANN, K F  
 PA (DEGS) DEGUSSA AG  
 CYC 13  
 PI EP 465861 / A 19920115 (199203)\*  
 R: AT BE CH DE ES FR GB IT LI LU NL SE  
 DE 4118217 A 19920123 (199205)  
 JP 04231193 A 19920820 (199241) 3<--  
 ADT EP 465861 A EP 1991-109694 19910613; DE 4118217 A DE 1991-4118217  
 19910604; JP 04231193 A JP 1991-161355 19910702  
 PRAI DE 1990-4021287 19900704; DE 1991-4118217 19910604  
 AB EP 465861 A UPAB: 19931006  
 A **brazing** alloy, for **brazing Cu** (alloys),  
 consists of 80-94% **Cu**, 4-8% **P**, 0-18% **Ag**, 0-10%  
**Sn** and 0-10% **In**, the novelty being the addition of 0.01-0.3% **Mn**, **Re**,  
**Hf**, **Nb**, **Ta**, **Mo**, **W** or **Fe** or 0.01-0.08% **Si**.  
 Pref. the addition comprises 0.05-0.2% **Hf** or **Mn** or 0.02-0.08% **Si**

ADVANTAGE - The addition provides much greater increase in ductility  
 than that obtd. with **Zr** or other conventional additives so that the  
**brazing** alloy can be easily cold worked to shaped parts, while the  
 flow and wetting properties are unaffected.  
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